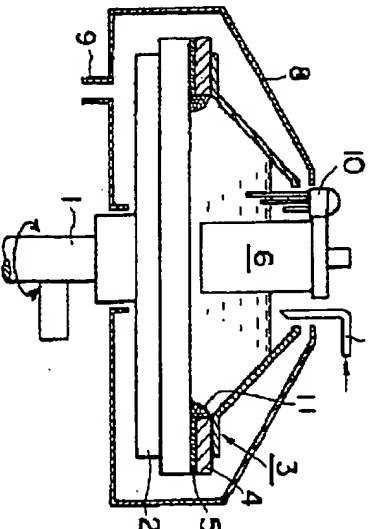


<p>1999-341860/29 L03 M13 SUMS 1997.10.15 SUMITOMO SPECIAL METALS CO LTD 1997.10.15 1997-299502(+1997JP-299502) (1999.05.11) C23C 18/31, B22F 1/02, H01L 21/60 Conductive film plating to micro plastic ball used on bump electrode in semiconductor package - involves using rotatable plating tank for repeated inversion of ball, contacting cathode provided at periphery C1999-101040</p>	<p>L(4-C10, 4-C11) M(13-B)</p> <p>Obtains high efficiency plating with highly precise uniform solder film.</p> <p><u>DESCRIPTION OF DRAWING(S)</u> e figure shows vertical section explanatory drawing of plating apparatus. (3) Rotary plating tank; (4) Cathode; (6) Anode.</p> 
<p><u>NOVELTY</u> A horizontal flat rotary plating tank (3), bears cathode (4) and anode (6) on its periphery and centre, respectively. Plating liquid is fed to tank which is rotated vertically at 50 - 800 rpm. Micro plastic balls of 1 mm or less of diameter, fed to the tank, are contacted to cathode with repeated inversions to form metal or alloy conductive film of thickness 0.5-5 μm.</p> <p><u>USE</u> To form conductive film on micro plastic ball used on bump electrode in semiconductor package.</p> <p><u>ADVANTAGE</u></p>	<p>(5pp3036DwgNo.1/2)</p> <p>JP 11124682-A</p>